



Features

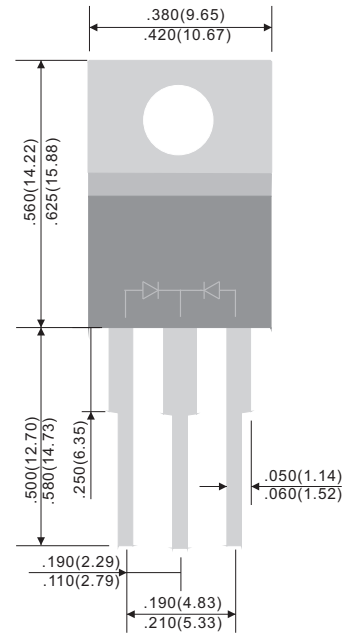
- High Junction Temperature Capability
- Case Material: Molded Plastic. UL Flammability
- **Pb-Free package is available**
RoHS product for packing code suffix "G"
Halogen free product for packing code suffix "H"
Classification Rating 94V-0 and MSL Rating 1
- Low Leakage Current
- Marking : type number

Maximum Ratings

- Operating Junction Temperature : 150°C
- Storage Temperature: - 50°C to +150°C
- Per diode Thermal Resistance 2.2°C/W Junction to Case
- Total Thermal Resistance 1.3°C/W Junction to Case
- Mounting Torque: 5 in-lbs Maximum

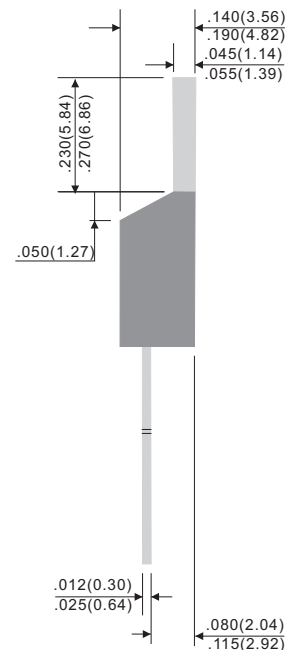
Catalog Number	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
MBR20150CT	150V	105V	150V

TO-220AB



Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward Current	$I_{F(AV)}$	20 A	$T_C = 155^\circ\text{C}$
Peak Forward Surge Current	I_{FSM}	180A	8.3ms, half sine wave
Maximum Instantaneous Forward Voltage MBR20150CT	V_F	.92V	$I_{FM} = 10A$ $T_J = 25^\circ\text{C}$
	V_F	.75V	$I_{FM} = 10A$ $T_J = 125^\circ\text{C}$
Maximum Reverse Current At Rated DC Blocking Voltage	I_R	25 μ A 5m A	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$



*Pulse Test: Pulse Width 380 μ sec, Duty Cycle 2%

Dimensions in inches and (millimeters)

20.0A SCHOTTKY BARRIER RECTIFIERS 150V

Fig. 1: Average forward power dissipation versus average forward current (per diode).

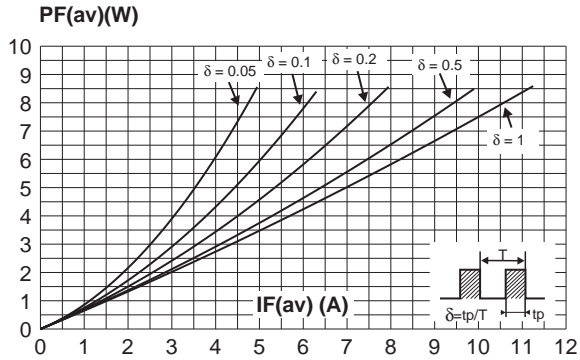


Fig. 2: Average forward current versus ambient temperature ($\delta = 0.5$, per diode).

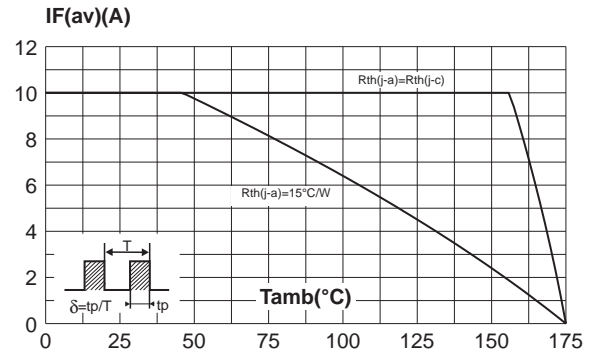


Fig. 3: Non repetitive surge peak forward current versus overload duration (maximum values, per diode).

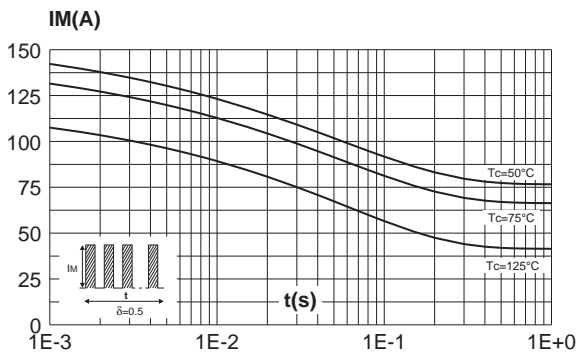


Fig. 4: Relative variation of thermal impedance junction to case versus pulse duration (per diode).

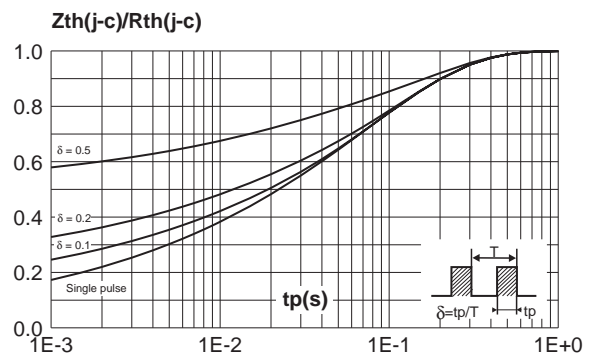


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values, per diode).

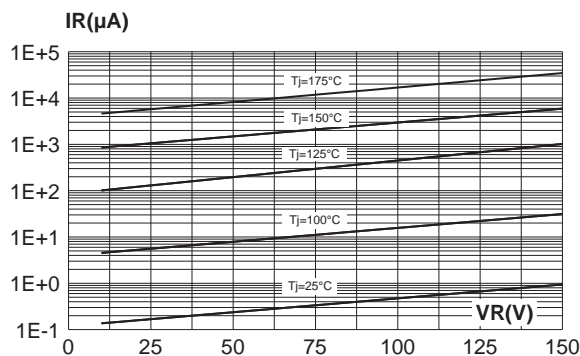


Fig. 6: Junction capacitance versus reverse voltage applied (typical values, per diode).

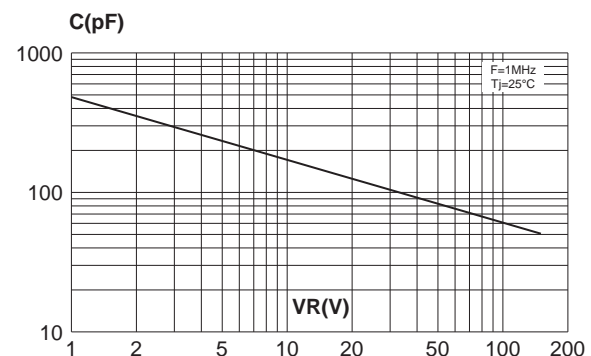


Fig. 7: Forward voltage drop versus forward current (maximum values, per diode).

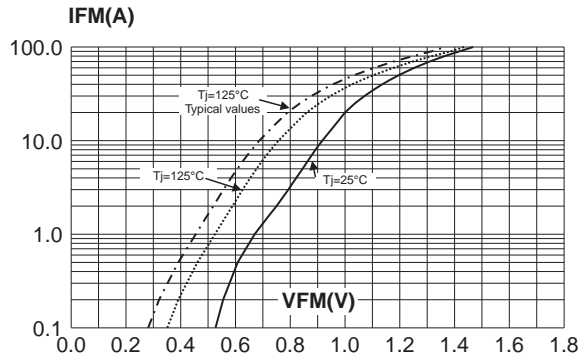


Fig. 8: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board, copper thickness: 35µm) (STPS20150CG only).

